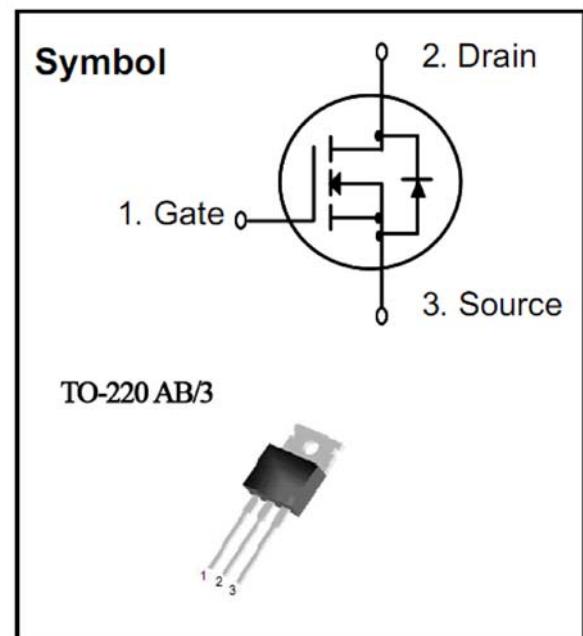


N-Channel MOSFET**Features**

- $R_{DS(on)}$ (Max 0.85 Ω)@ $V_{GS}=10V$
- Gate Charge (Typical 38 nC)
- Maximum Junction Temperature Range (150 °C)

**Absolute Maximum Ratings**

Symbol	Parameter	Value	Units
V_{DSS}	Drain to Source Voltage	500	V
I_D	Continuous Drain Current(@ $T_C = 25^\circ C$)	8.0	A
	Continuous Drain Current(@ $T_C = 100^\circ C$)	5.1	A
I_{DM}	Drain Current Pulsed	32 ^{..1)}	A
V_{GS}	Gate to Source Voltage	± 25	V
E_{AS}	Single Pulsed Avalanche Energy	320 ^{..2)}	mJ
E_{AR}	Repetitive Avalanche Energy	13.4 ^{..1)}	mJ
dv/dt	Peak Diode Recovery dv/dt	5.5 ^{..3)}	V/ns
P_D	Total Power Dissipation(@ $T_C = 25^\circ C$)	134	W
	Derating Factor above 25 °C	1.08	W/°C
T_{STG}	Operating Junction Temperature	-55 ~ 150	°C
T_J	Storage Temperature	150	°C

Notes

^{1)..} Repeativity rating : pulse width limited by junction temperature

^{2)..} L = 9.0 mH, $I_{AS} = 8.0 A$, $V_{DD} = 50 V$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ C$

^{3)..} $I_{SD} \leq 8.0 A$, $di/dt \leq 300 A/\mu s$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ C$



Thermal Characteristics

Symbol	Parameter	Value			Units
		Min.	Typ.	Max.	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	-	-	0.93	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient*	-	0.5	-	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	-	-	62.5	°C/W

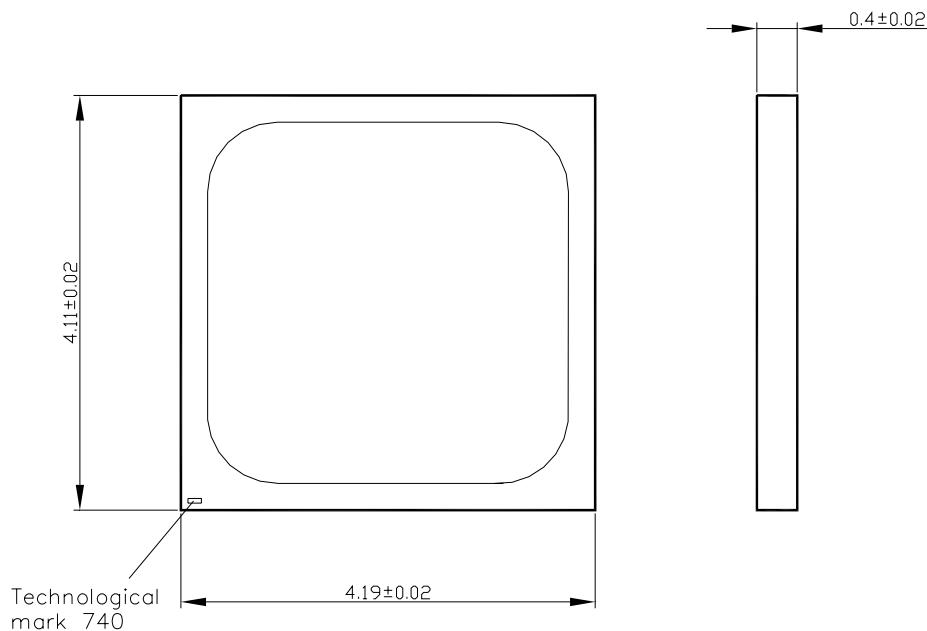
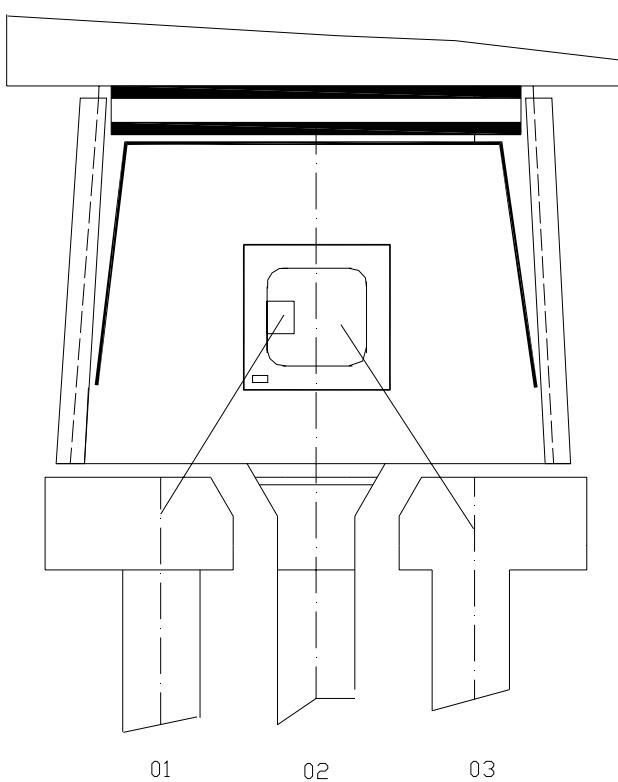
* When mounted on the minimum pad size recommended (PCB Mount)

Source-Drain Diode Characteristics and Maximum Ratings

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I_S	Maximum Continuous Source-Drain Diode Forward Current	$I_S = 8.0 \text{ A}, V_{GS} = 0 \text{ V}$	-	-	8.0	A
I_{SM}	Maximum Pulsed Source-Drain Diode Forward Current		-	-	32	
V_{SD}	Drain-Source Diode Forward Voltage	$I_S = 8.0 \text{ A}, V_{GS} = 0 \text{ V}$, $dI/dt = 100 \text{ A/us}$ Pulse Width $\leq 300\mu\text{s}$, $Q > 50$	-	-	1.5	V
t_{rr}	Reverse Recovery Time		-	270	-	ns
Q_{rr}	Reverse Recovery Charge		-	1.89	-	uC

Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	500	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Breakdown Voltage Temperature coefficient	$I_D = 250 \mu\text{A}$, referenced to 25°C	-	0.50	-	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}} = 500 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$	-	-	1	μA
		$V_{\text{DS}} = 400 \text{ V}$, $T_C = 125^\circ\text{C}$	-	-	10	μA
I_{GSS}	Gate-Source Leakage, Forward	$V_{\text{GS}} = 25 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$	-	-	100	nA
	Gate-source Leakage, Reverse	$V_{\text{GS}} = -25 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$	-	-	100	nA
On Characteristics						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250 \mu\text{A}$	2.0	-	4.0	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-state Resistance	$V_{\text{GS}} = 10 \text{ V}$, $I_D = 4.0 \text{ A}$	-	0.70	0.85	Ω
g_{FS}	Forward Transconductance	$V_{\text{GS}} = 40 \text{ V}$, $I_D = 4.0 \text{ A}$ Pulse Width $\leq 300\text{us}$, $Q > 50$	-	7.0	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{GS}} = 0 \text{ V}$, $V_{\text{DS}} = 25 \text{ V}$, $f = 1 \text{ MHz}$	-	1570	2040	pF
C_{oss}	Output Capacitance		-	150	195	
C_{rss}	Reverse Transfer Capacitance		-	15	20	
Dynamic Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}} = 400 \text{ V}$, $I_D = 8.0 \text{ A}$, $R_G = 25 \Omega$ Pulse Width $\leq 300\text{us}$, $Q > 50$	-	25	60	ns
t_r	Rise Time		-	75	160	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	125	260	
t_f	Fall Time		-	75	160	
Q_g	Total Gate Charge	$V_{\text{DS}} = 400 \text{ V}$, $V_{\text{GS}} = 10 \text{ V}$, $I_D = 8.0 \text{ A}$ Pulse Width $\leq 300\text{us}$, $Q > 50$	-	38	50	nC
Q_{gs}	Gate-Source Charge		-	8	-	
Q_{gd}	Gate-Drain Charge(Miller Charge)		-	13	-	

Chip size**Package Chip**

Package Dimensions TO-220 AB/3

